

March 4, 2025

Investor Presentation

Berenberg EU Opportunities Conference 2025

London



SUSS at a glance



- Hidden champion headquartered in Germany with 75 years track record of innovation and growth
- Key technology provider for semiconductor frontend and advanced backend industry, benefiting from structural growth drivers such as Artificial Intelligence
- Global customer base with largest share of business in Asia
- Strategic partner for global semiconductor IDMs and foundries
- Innovator with relevant network to research institutes and universities

SUSS is part of our digital life!

Management Board of SUSS MicroTec SE





- Finance & Controlling
- Legal & Compliance
- Internal Audit
- Investor Relations
- IT
- ESG



- Sales and Service
- Strategy
- HR
- Business Units:
 Advanced Backend Solutions,
 Photomask Solutions



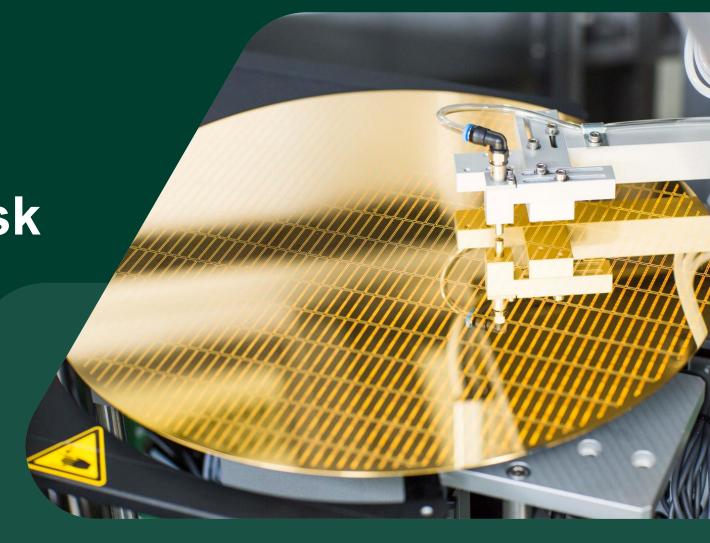
- R&D
- Purchasing
- Production
- Logistics
- Quality Management
- Product Center
- Facility Management

Our corporate vision defines our strategies



Leader in enabling innovative advanced backend & photomask solutions

Our vision

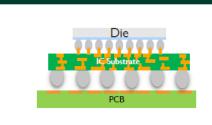


Our world are the semiconductor frontend and backend process steps











Wafer fabrication

Front-end-of-line Wafer process

- Deposition/coating
- Cleaning
- Patterning/lithography¹
- Etching
- Implantation
- Annealing
- · Permanent bonding
- Temporary bonding
- CMP polishing

From middle-of-line to back-end-of-line

Advanced packaging

- Deposition/coating
- Cleaning
- Patterning/lithography
- Etching
- Annealing
- CMP polishing
- · Permanent bonding
- Temporary bonding
- Wafer level packaging
- · Wafer dicing
- Panel-level packaging

Final packaging

- Mounting
- · Wire bonding
- Molding encapsulation
- · Trim & forming

¹ Only related to Photomask processing Source: Yole, Lithography and Bonding Equipment for More than Moore 2022

Our two segments, mainly serving the semiconductor industry



Frontend

Segments Photomask Solutions



Advanced Backend

Advanced Backend Solutions







Products



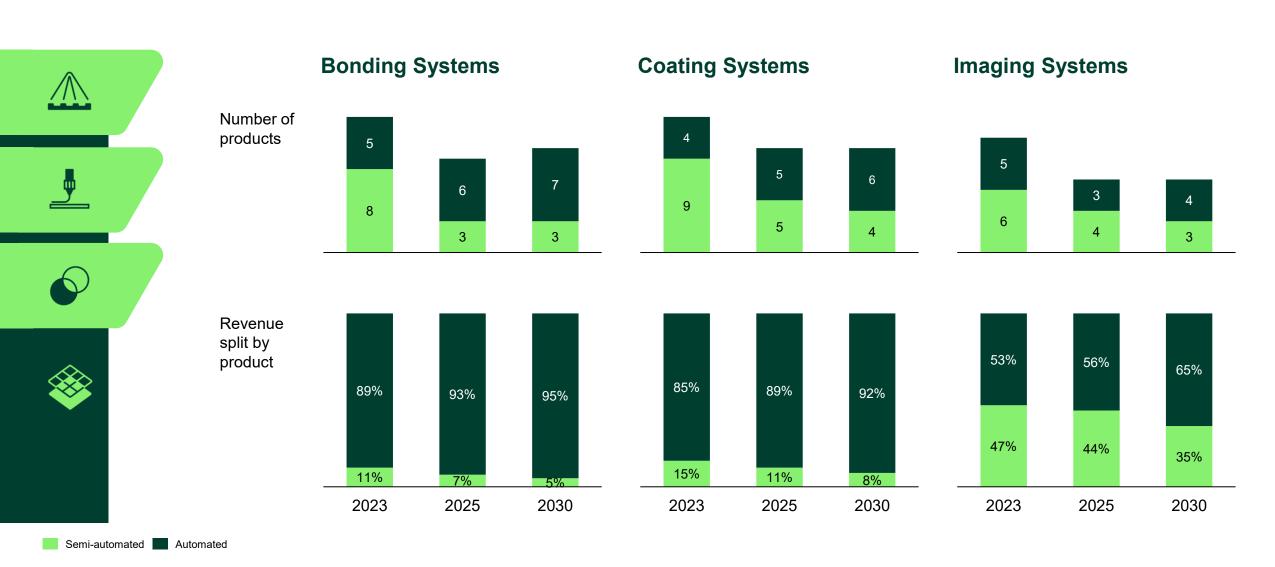






Focus on high-volume manufacturing markets while semi-automated tools will be phased-out during next years in Advanced Backend Solutions business unit





Full range of bonding solutions by SUSS



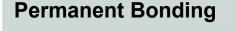








Temporary Bonding



















Mech. De-bonding (semi-auto)
DB12T





SUSS hybrid bonding solutions – understanding customer's needs









Wafer-to-wafer HB XBS300 W2W

Product launch: 10/2022 Target customers: HVM

Die-to-wafer/wafer-to-wafer HB XBC300 Gen2 D2W/W2W

Product launch: 05/2024
Target customers: Research institutes, R&D teams of HVM

Die-to-wafer HB XBC300 Gen2 D2W

Product launch: H1/2025 Target customers: HVM

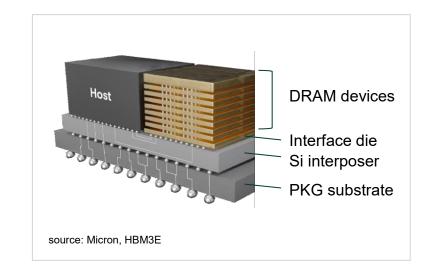
We optimize our product solutions to serve our customer's device and manufacturing needs.

HBM roadmap enables SUSS to grow in existing and new markets



10

in € million	НВМ3Е	HBM4	HBM4E	HBM5
Expected SOP	2024	2025	2026 or 2027	2027 or 2028
# of DRAM layer acc. to JEDEC	8/12	12	16	16/20
Bonding type in DRAM stack	ТСВ	TCB	TCB or HB	НВ
Thinning of DRAM devices	TBDB	TBDB	TBDB	TBDB



Relevance for SUSS:



TBDB remains a crucial process for thinning of DRAM devices used in HBM cube

Growth of existing SUSS TBDB business in line with general HBM market growth

2

Increase of layer number in HBM cube triggers more TBDB capacity for thinning of DRAM devices

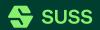
Additional growth of SUSS TBDB business in line with higher layer in HBM cube

3

Hybrid bonding will gradually replace Thermal Compression bonding for stacking of DRAM devices

Expansion into this market offers new growth opportunities with SUSS HB solutions

TCB: Thermal compression bonding, HB: hybrid bonding, TBDB: Temporary bonding & de-bonding



We have built up additional temporary bonding capacity in Taiwan

- We added 50+ people in Hsinchu in order increase manufacturing capacity for temporary bonders
- First temporary bonder 'made in Taiwan' has been completed at the beginning of March 2024
- Full capacity available since Q3-2024
- Total manufacturing capacity for temporary bonding equipment (bonder, debonder and cleaner) in Sternenfels and Hsinchu allows us to generate yearly sales of ~ €150 million



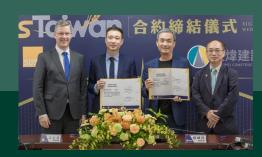
New, larger production site in Zhubei (Taiwan) prepares us for further targeted growth



1

Signing

of long-term lease agreement for new production site in Zhubei took place on October 23, 2024.



2

Completion

of shell is scheduled for the end of 2024. We will then carry out cleanroom and office installations with expected CAPEX of € 15-20 million.

3

Production start

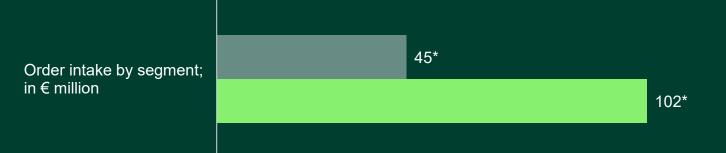
at the new site is expected in the second half of 2025. The new factory offers the potential to double production capacity under clean room conditions to ~6,300 m².



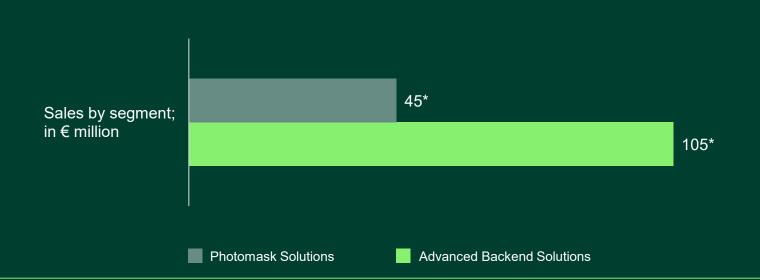
Q4 2024 has been the best quarter in terms of sales and order intake in the company's history





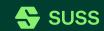


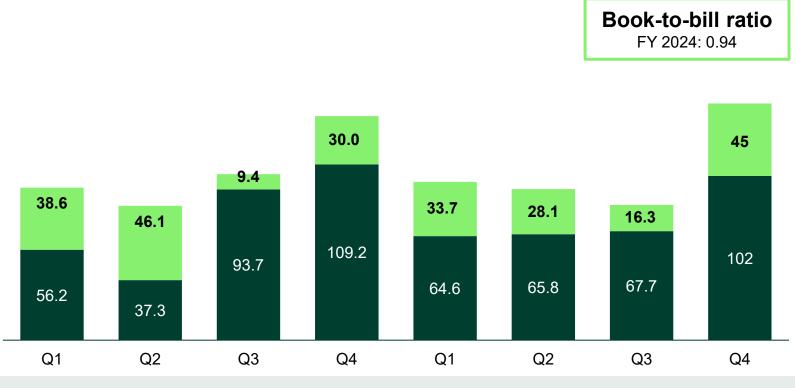




* Preliminary and unaudited

Order intake by segment (in € m)







Advanced Backend Solutions Photomask Solutions

€ 420.5m

FY 2023

* Preliminary; 2023 order intake adjusted for MicroOptics segment

- Strong Q4 2024 order momentum in Photomask Solutions, mainly to support capacity expansion at key customers
- Within Advanced Backend Solutions, order intake in Q4 2024 was well distributed across the Imaging, Coating and Bonding product lines
 - Imaging systems: strong CoWoSrelated demand for UV Projection Scanner
 - Coating systems: improved order situation continued in Q4 2024
 - Bonding systems: very strong yearend finish, supporting Al-related capacity expansion (HBM, CoWoS) and other customers

Order book is a very solid basis for the 2025 financial year



Order book as of December 31, 2024, of which the vast majority is expected to be executed in 2025





* Preliminary and unaudited

Photomask Solutions

Advanced Backend Solutions

Sales and EBIT margin are expected to exceed 2024 guidance



Expected financial performance in 2024, based on preliminary unaudited results

preliminary, unaudited results (as of January 16, 2025) Sales in € million **Actual 2023:** € 304.3 million **Guidance:** Sales of € 380–410 million

Gross profit margin in % ~40.0 **Actual 2023:** 34.1% **Guidance:** Gross profit margin of 38–40%



Division Overview 9M 2024



Advanced Backend Solutions

in € million	9M.2024	9M.2023
Order intake	198.1	187.1
Order book	274.2	244.9
Sales	208.8	146.9
Gross profit	86.8	51.7
Gross profit margin	41.6%	35.2%
EBIT	33.3	10.2
EBIT margin	16.0%	6.9%

Photomask Solutions

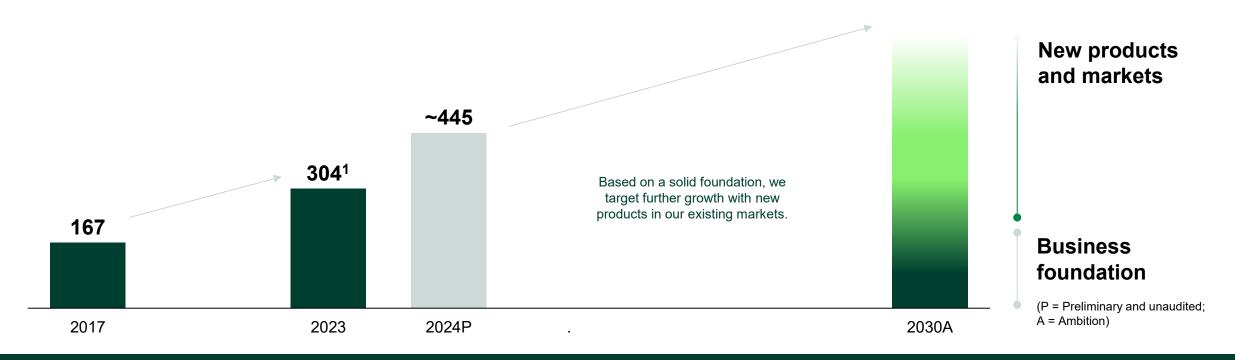
in € million	9M.2024	9M.2023
Order intake	78.1	94.1
Order book	156.7	169.9
Sales	86.5	55.5
Gross profit	30.6	16.2
Gross profit margin	35.5%	29.2%
EBIT	17.9	6.2
EBIT margin	20.7%	11.2%

- Order intake up 5.9% year-on-year, despite a € 29 million decline in orders from Chinese customers; orders for coating systems improved in Q3
- Significant sales growth of € 61.9 million or 42.1% versus 9M 2023, mainly driven by execution of Al-connected bonder orders received in H2 2023; bonder sales thus almost tripled year-on-year
- Gross profit margin improved by 6.4pp to 41.6% thanks to high sales volume and favorable product and customer mix; all three quarters with gross profit margin >40%

- Expected normalization of Chinese customers' order behavior leads to € 16.0 million decline in order intake to € 78.1 million
- Strong order book level of ~ € 157 million provides high visibility and capacity utilization through mid-2025
- Ability to execute orders allows for significant sales growth of 55.9%
- Gross profit margin and EBIT margin benefited from strong product and customer mix as well as from very high sales level

Based on our business foundation we see further potential beyond







Major growth drivers 2023

Converting high order backlog in Photomask Solutions and Bonder business into sales growth 2

Major growth drivers 2024/2025

- Bonding (especially with regard to Al-driven demand for temporary bonders)
- Photomask Solutions

Major growth drivers 2030

- General expected market growth in our core businesses (lithography, bonding, photomask)
- Hybrid Bonding
- Wafer Cleaning

1 Excluding MicroOptics

Investor Relations information



Conference Calendar

- March 6, 2025

 Berenberg EU Opportunities Conference, London
- April 2, 2025

 Metzler Small Cap Days, Frankfurt (IR-only)
- May 21, 2025
 Investor Roadshow, Chicago
- May 22, 2025
 Berenberg European Conference, New York City

Financial Calendar

- March 27, 2025
 Annual Report 2024
- May 8, 2025
 Q1 Report 2025
- June 3, 2025
 Annual General Meeting
- August 7, 2025
 Half Year Report 2025
- November 6, 2025
 Q3 Report 2025

There may be changes to the SUSS conference schedule.

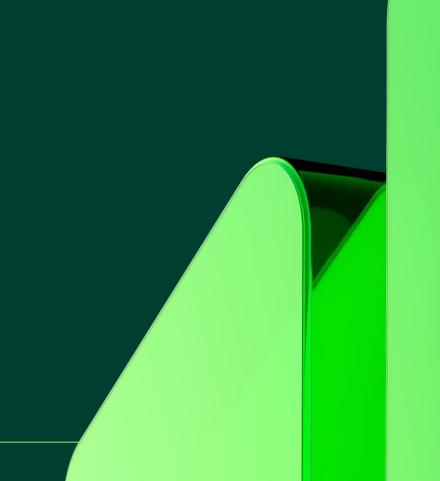
Disclaimer



This presentation contains forward-looking statements relating to the business. financial performance and earnings of SUSS MicroTec SE and its subsidiaries and associates.

Forward-looking statements are based on current plans. estimates. projections and expectations and are therefore subject to risks and uncertainties. most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec SE. Consequently. actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements.

SUSS MicroTec SE does not intend or accept any obligation to publish updates of these forward-looking statements.



Thank you

Growing Innovation



Sven Koepsel

VP Investor Relations & Communications

Tel.: +49 89 32007-151

E-mail: sven.koepsel@suss.com



Florian Mangold

Manager Investor Relations

Tel.: +49 89 32007-306

E-mail: florian.mangold@suss.com

